L Number	Hits	Search Text	DB	Time stamp
-	48	(ceramic adj substrate) and	USPAT;	2004/07/21 22:46
		((thermosetting and inorganic) with	US-PGPUB;	
		(filler or underfill))	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	37		USPAT;	2004/05/07 11:52
		inorganic) with (filler or underfill))	US-PGPUB; EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	27	((ceramic adj substrate) and	USPAT;	2003/03/24 00:03
		((thermosetting and inorganic) with	US-PGPUB;	
		(filler or underfill))) not ((ceramic adj	EPO; JPO;	
		substrate) and ((epoxy and inorganic) with	DERWENT;	
		(filler or underfill)))	IBM_TDB	
-	0	(====================================	USPAT;	2003/03/24 00:26
		thermosetting) and inorganic) with	US-PGPUB;	
		(capsulant))	EPO; JPO;	
			DERWENT; IBM TDB	
_	0	(ceramic adj substrate) and (((epoxy or	USPAT;	2003/03/24 00:26
	0	thermosetting) and inorganic) with	US-PGPUB;	2000,00,24 00.20
		(capsulent))	EPO; JPO;	
		(**************************************	DERWENT;	
			IBM_TDB	
-	0		USPAT;	2003/03/24 00:26
		thermosetting) and inorganic) with	US-PGPUB;	
		(capsulant))	EPO; JPO;	
			DERWENT;	
	,	(conomic odd board) and (((onour or	IBM_TDB USPAT;	2003/03/24 01:20
-	4	(ceramic adj board) and (((epoxy or thermosetting) and inorganic) with (fill	US-PGPUB;	2003/03/24 01:20
		or underfill))	EPO; JPO;	
		or underlift,	DERWENT;	
			IBM TDB	
-	1	("6356453").PN.	USPĀT	2003/03/24 01:32
-	1	("20010030059").PN.	USPAT;	2003/03/24 01:32
			US-PGPUB	
] -	1	("20020096759").PN.	USPAT;	2003/10/07 13:32
	1	("5831833").PN.	US-PGPUB USPAT;	2003/10/07 13:32
-	T	("5651655").PN.	US-PGPUB	2003/10/07 13:32
_	535	((ceramic or glass adj epoxy) near3	USPAT;	2004/05/07 16:55
	555	substrate) and ((epoxy and inorganic) with	US-PGPUB;	2001,00,01 20100
		(filler or underfill or resin))	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	127	1 ' ' ' ' ' ' ' ' ' ' ' ' ' ' ' ' ' ' '	USPAT;	2003/10/07 16:18
		substrate) and ((epoxy and inorganic) with	US-PGPUB;	
		(filler or underfill or resin))) and (semiconductor and (resistor or capacitor	EPO; JPO; DERWENT;	
		or passive))	IBM TDB	
_	0		USPAT;	2003/10/07 15:15
		substrate) and ((epoxy and inorganic) with	US-PGPUB;	
		(filler or underfill or resin))) and	EPO; JPO;	
		(semiconductor and (resistor or capacitor	DERWENT;	
		or passive))) not (((ceramic or glass adj	IBM_TDB	
		epoxy) near3 substrate) and ((epoxy and		
		inorganic) with (filler or underfill or		
	400	resin)))	HODAM.	2003/10/07 15:15
-	408	(((ceramic or glass adj epoxy) near3 substrate) and ((epoxy and inorganic) with	USPAT; US-PGPUB;	2003/10/0/ 13:15
		(filler or underfill or resin))) not	EPO; JPO;	
		((((ceramic or glass adj epoxy) near3	DERWENT;	
		substrate) and ((epoxy and inorganic) with	IBM TDB	
		(filler or underfill or resin))) and	_	
		<pre>(semiconductor and (resistor or capacitor or passive)))</pre>		

-	4406		USPAT;	2004/07/21 22:49
		substrate) and (epoxy with (filler or	US-PGPUB;	
}		underfill or resin))	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	852		USPAT;	2003/10/07 16:18
		substrate) and (epoxy with (filler or	US-PGPUB;	
	1	underfill or resin))) and (semiconductor	EPO; JPO;	
		and (resistor or capacitor or passive))	DERWENT;	
			IBM_TDB	
-	725		USPAT;	2003/10/07 16:34
		substrate) and (epoxy with (filler or	US-PGPUB;	
		underfill or resin))) and (semiconductor	EPO; JPO;	
		and (resistor or capacitor or passive))) not (((ceramic or glass adj epoxy) near3	DERWENT;	
			IBM_TDB	
		substrate) and ((epoxy and inorganic) with		
	629	(filler or underfill or resin))) 257/728.ccls.	HCDAM.	2004/05/07 17:12
-	629	25///28.CCIS.	USPAT;	2004/05/07 17:12
			US-PGPUB; EPO; JPO;	
			DERWENT;	
			IBM TDB	
l _	351	257/729.ccls.	USPAT;	2003/10/16 17:41
-	331	201, 129,0013.	US-PGPUB;	2003/10/10 1/:41
	1		EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	1767	257/678.ccls.	USPAT;	2003/10/16 17:41
	1,0,	2077 070100131	US-PGPUB;	2003,10,10 1,.11
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	640	257/687.ccls.	USPAT;	2003/10/16 17:41
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	1394	257/690.ccls.	USPAT;	2003/10/16 17:41
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	961	257/691.ccls.	USPAT;	2003/10/16 17:41
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	1044	257/7001-	IBM_TDB	2004/07/20 15 22
-	1341	257/700.ccls.	USPAT;	2004/07/22 15:30
			US-PGPUB; EPO; JPO;	
			DERWENT;	
1			IBM TDB	
l _	641	257/703.ccls.	USPAT;	2003/10/16 17:41
		20., / 00.0020.	US-PGPUB;	2000,10,10 17.41
			EPO; JPO;	
			DERWENT;	
1			IBM TDB	
-	1056	257/701.ccls.	USPAT;	2003/10/16 17:41
1	1		US-PGPUB;	
1			EPO; JPO;	
1			DERWENT;	
			IBM_TDB	
-	465	257/705.ccls.	USPAT;	2003/10/16 17:41
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
		(#C507000#) PV	IBM_TDB	0004/00/00 00 00
-	1	("6587008").PN.	USPAT	2004/03/30 15:28
_	0 1	("US-5795799-\$.DID.").PN.	USPAT	2004/05/07 11:25
<u> </u>	L	US-5795799-\$.DID.	USPAT	2004/05/07 11:25

_	286		USPAT;	2004/05/07 16:56
		((epoxy and inorganic) same (filler or	US-PGPUB;	
		underfill or resin))	EPO; JPO;	
			DERWENT;	
	715	/	IBM_TDB USPAT;	2004/05/07 16:57
-	715	(ceramic near3 substrate) and ((epoxy and inorganic) SAME (filler or underfill or	USPAT; US-PGPUB;	2004/05/07 16:57
		resin))	EPO; JPO;	
		lesin),	DERWENT;	
			IBM TDB	
_	145	(((glass adj epoxy) near3 substrate) and	USPAT;	2004/05/07 16:57
	1	((epoxy and inorganic) same (filler or	US-PGPUB;	
		underfill or resin))) not ((ceramic near3	EPO; JPO;	
		substrate) and ((epoxy and inorganic)	DERWENT;	
	1	SAME (filler or underfill or resin)))	IBM_TDB	
-	678	257/687.ccls.	USPAT;	2004/05/07 17:12
<u> </u>			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
		055/500	IBM_TDB	0004/05/05 45 40
j -	1467	257/690.ccls.	USPAT;	2004/05/07 17:12
			US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
_	1040	257/691.ccls.	USPAT;	2004/05/07 17:12
	1010	237, 031.0015.	US-PGPUB;	2001,00,01 1,112
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	1417	257/700.ccls.	USPAT;	2004/05/07 17:13
			US-PGPUB;	
			EPO; JPO;	l
			DERWENT;	-
	662	257/702 0010	IBM_TDB	2004/05/07 17-12
-	662	257/703.ccls.	USPAT; US-PGPUB;	2004/05/07 17:13
!			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	1110	257/701.ccls.	USPAT;	2004/05/07 17:13
			US-PGPUB;	
			EPO; JPO;	
[i			DERWENT;	
		058/805	IBM_TDB	0001105155
-	475	257/705.ccls.	USPĀT;	2004/05/07 17:13
[:			US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
<u>-</u>	674	257/728.ccls.	USPAT;	2004/05/07 17:13
			US-PGPUB;	,,,,,,,,,
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	360	257/729.ccls.	USPĀT;	2004/05/07 17:31
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
_	1938	257/678.ccls.	<pre>IBM_TDB USPAT;</pre>	2004/05/07 18:23
_	1 230	237, 070.0013.	US-PGPUB;	2004/03/01 10:23
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	74	(ceramic adj substrate) and	USPAT;	2004/05/10 11:48
		((thermosetting and inorganic) with	US-PGPUB;	
		(filler or underfill))	EPO; JPO;	
			DERWENT;	
		(#64.69.45.6#)	IBM_TDB	0004408405
<u>-</u>	1	("6163456").PN.	USPAT	2004/07/22 15:18

-	4821	((ceramic or (glass adj epoxy)) near3	USPAT;	2004/07/21 22:49
		substrate) and (epoxy near5 (filler or	US-PGPUB;	
		underfill or resin))	EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	142	(((ceramic or (glass adj epoxy)) near3	USPĀT;	2004/07/22 12:59
		substrate) and (epoxy near5 (filler or	US-PGPUB;	
		underfill or resin))) and (epoxy near5	EPO; JPO;	
		inorganic)	DERWENT;	
			IBM TDB	
_	1	"2000397728"	JPO;	2004/07/22 12:26
	_	200037720	DERWENT	2001,01,22 12.20
	1	"6160526".PN.	USPAT	2004/07/22 12:31
	1 1	"6060150".PN.	USPAT	2004/07/22 12:31
-	1	"6038133".PN.	USPAT	2004/07/22 12:31
-	1		USPAT	2004/07/22 12:32
-				
-	293		USPAT;	2004/07/22 12:58
		substrate) and (epoxy near5 (filler or	US-PGPUB;	<u> </u>
		underfill or resin))) and (epoxy with	EPO; JPO;	
		inorganic)	DERWENT;	
			IBM_TDB	
-	150	((((ceramic or (glass adj epoxy)) near3	USPAT;	2004/07/22 13:00
		substrate) and (epoxy near5 (filler or	US-PGPUB;	
		underfill or resin))) and (epoxy with	EPO; JPO;	
		inorganic)) not ((((ceramic or (glass adj	DERWENT;	
		epoxy)) near3 substrate) and (epoxy near5	IBM TDB	
		(filler or underfill or resin))) and	_	
	1	(epoxy near5 inorganic))		
l _	143		USPAT;	2004/07/22 15:27
	1	substrate) and (epoxy near5 (filler or	US-PGPUB;	2001,01,22 13.21
	ì	underfill or resin))) and (epoxy near5	EPO; JPO;	
		inorganic)	DERWENT;	
		Inorganic,	IBM TDB	
	1	/#5705700#\ DN	USPAT	2004/07/20 15:10
_	1	("5795799").PN.		2004/07/22 15:19
-	1	(, , , , , , , , , , , , , , , , , , ,	USPAT	2004/07/22 15:21
-	1	("20020096759").PN.	USPAT;	2004/07/22 15:22
	_		US-PGPUB	
-	2	((alo or (aluminum adj oxide) or beo)	USPAT;	2004/07/22 15:30
		near3 substrate) and (epoxy near5 (filler	US-PGPUB;	
		or underfill or resin)) and (epoxy near5	EPO; JPO;	
		inorganic)	DERWENT;	
			IBM_TDB	
-	0	257/701ccls.	USPĀT;	2004/07/22 15:31
			US-PGPUB;	
	1		EPO; JPO;	
	1		DERWENT;	
	1		IBM TDB	
-	1132	257/701.ccls.	USPĀT;	2004/07/22 15:31
			US-PGPUB;	
	1		EPO; JPO;	
	1		DERWENT;	
	1		IBM TDB	
-	667	257/703.ccls.	USPAT;	2004/07/22 15:31
]		US-PGPUB;	
			EPO; JPO;	
	1		DERWENT;	
	1			
1_	478	257/705.ccls.	IBM_TDB USPAT;	2004/07/22 15:31
_	4/8	201/100.0018.	, .	2004/01/22 15:31
			US-PGPUB;	
			EPO; JPO;	
	<u> </u>		DERWENT;	
		055 (500	IBM_TDB	1
-	692	257/728.ccls.	USPAT;	2004/07/22 15:31
1			US-PGPUB;	1
			EPO; JPO;	
			DERWENT;	
1			IBM_TDB	
-	372	257/729.ccls.	USPĀT;	2004/07/22 15:31
1			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
L	1	<u> </u>		

_	2014	257/678.ccls.	USPAT;	2004/07/22 15:32
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	692	257/687.ccls.	USPAT;	2004/07/22 15:32
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	1494	257/690.ccls.	USPAT;	2004/07/22 15:32
			US-PGPUB;	
			EPO; JPO;	İ
			DERWENT;]
			IBM_TDB	·
-	1083	257/691.ccls.	USPAT;	2004/07/22 15:32
			US-PGPUB;	
1			EPO; JPO;	
•			DERWENT;	
			IBM_TDB	
-	1448	257/700.ccls.	USPAT;	2004/07/22 15:34
	İ		US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	